

REMARKS

By this amendment, claims 3 and 10 have been amended. Accordingly, claims 3-11 are currently pending in the application, of which claims 3 and 10 are independent claims.

In view of the above amendments and the following Remarks, Applicants respectfully request reconsideration and timely withdrawal of the pending objections and rejections for the reasons discussed below.

Rejections Under 35 U.S.C. §112, first paragraph

Claims 3-9 stand rejected under 35 U.S.C. §112, first paragraph as failing to comply with the written description requirement. Applicants respectfully traverse this rejection for at least the following reasons.

In the Office Action, the Examiner stated “The limitation of “... wherein the pad auxiliary layer is formed on a same layer as the gate wiring” ... is not described in the specification”. This assertion is respectfully disagreed with.

According to the third embodiment of the present application (Figs. 6 and 7), the pad auxiliary layer 25 is “formed on the same layer as the elements 22, 24 and 26 of the gate wiring” (Specification, page 13, lines 20-21). Thus, it is submitted that the above-mentioned claimed feature is disclosed in the specification. For clarification and better wording purposes, in this response, claim 3 has been amended to recite “wherein the pad auxiliary layer and the gate wiring are formed on a same surface”.

Accordingly, Applicants respectfully request withdrawal of the 35 U.S.C. §112, first paragraph rejection of claims 3-9.

Rejections Under 35 U.S.C. §102

Claims 3-8, 10 and 11 stand rejected under 35 U.S.C. §102(b) as being anticipated by U. S. Patent No. 6,038,003 issued to Kim, *et al.* (“Kim”). Applicants respectfully traverse this rejection for at least the following reasons.

With respect to claims 3-8, independent claim 3 recites “a pad auxiliary layer formed protruding a predetermined height under the data pads, wherein *the pad auxiliary layer and the gate wiring are formed on a same surface*”.

In this regard, the Examiner stated “a pad auxiliary layer (133a) formed protruding a predetermined height under the data pads 125, wherein the pad auxiliary layer 133a is formed on the gate insulting layer 117a” (Office Action, page 4).

However, as previously mentioned, claim 3 recites that the pad auxiliary layer and the gate wiring are formed on a same surface. In this regard, Kim discloses the gate wiring 111 formed on the substrate 101 and the asserted pad auxiliary layer 133 formed on the gate oxide film 177a.

For this reason, Kim fails to disclose or suggest “*the pad auxiliary layer and the gate wiring are formed on a same surface*”. Thus, it is submitted that claim 3 is patentable over Kim. Claims 4-8 that are dependent from claim 3 would be also patentable at least for the same reason.

With respect to claims 10 and 11, in this response, claim 10 has been amended to recite “wherein portions of the protection layer surrounding the data pads are completely removed to form a void surrounding each data pad”.

An example of this claimed feature is shown in Fig. 5, in which "... the protection layer 70 are removed from a specific portion P of the pad portions where the data pad 68 are formed ... The same effects as with the first embodiment are achieved with this structure" (Specification, page 13, lines 3-9).

Regarding "The same effects as with the first embodiment", the specification describes "... thereby preventing contact defects and limiting the contact resistance between the probe pin 200 and the auxiliary data pads 88 during panel testing in the LCD manufacturing process" (Specification, page 12, lines 12-15)

In this regard, Kim describes "... the source pad 125 may be fully exposed" but does not disclose or suggest completely removing portions of the protection layer surrounding the data pads to *form a void surrounding each data pad*, as shown in Fig. 5. Thus, it is submitted that claim 10 is patentable over Kim. Claim 11 that is dependent from claim 10 would be also patentable at least for the same reason.

Accordingly, Applicants respectfully request withdrawal of the 35 U.S.C. §102(b) rejection of claims 3-8, 10 and 11.

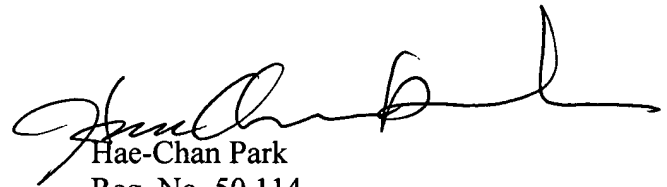
CONCLUSION

Applicants believe that a full and complete response has been made to the pending Office Action and respectfully submits that all of the stated objections and grounds for rejection have been overcome or rendered moot. Accordingly, Applicants respectfully submit that all pending claims are allowable and that the application is in condition for allowance.

Should the Examiner feel that there are any issues outstanding after consideration of this response, the Examiner is invited to contact the Applicants' undersigned representative at the number below to expedite prosecution.

Prompt and favorable consideration of this Reply is respectfully requested.

Respectfully submitted,



Hae-Chan Park
Reg. No. 50,114

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McGuireWoods LLP
1750 Tysons Boulevard
Suite 1800
McLean, VA 22102-4215
Tel: 703-712-5365
Fax: 703-712-5280
HCP:WSC/bjb